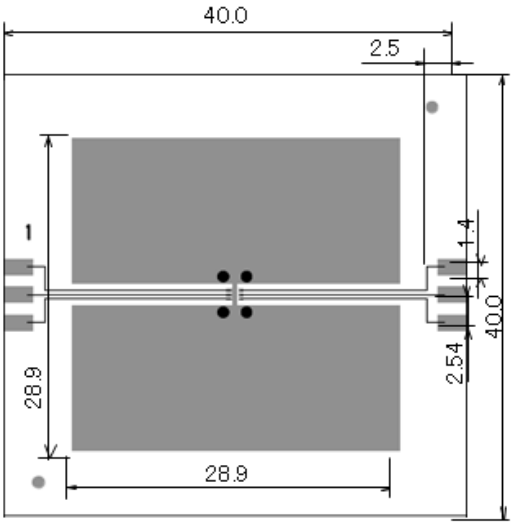
● DFN1515-6A Power Dissipation

Power dissipation data for the DFN1515-6A is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as the reference data taken in the following condition.

1. Measurement Condition

Condition	: Mount on a board
Ambient	: Natural convection
Soldering	: Lead (Pb) free
Board Dimensions	: 40 x 40 mm (1600mm^2 in one side)
Metal Area	: 1st Meter layer about 50% 2nd Inner Metal layer about 50% 3rd Inner Metal layer about 50% 4th Metal layer about 50% Each heat sink back metal is connected to the Inner layers respectively.
Material	: Glass Epoxy (FR-4)
Thickness	: 1.6 mm
Through-hole	: 4 x 0.8 Diameter

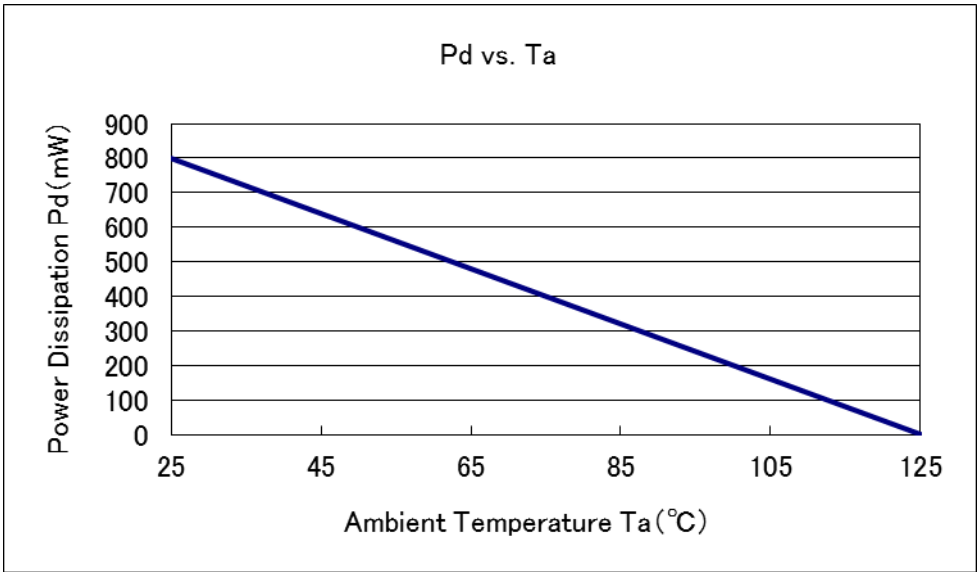


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (Tj max = 125℃)

Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	800	125.00
85	320	
125	0	

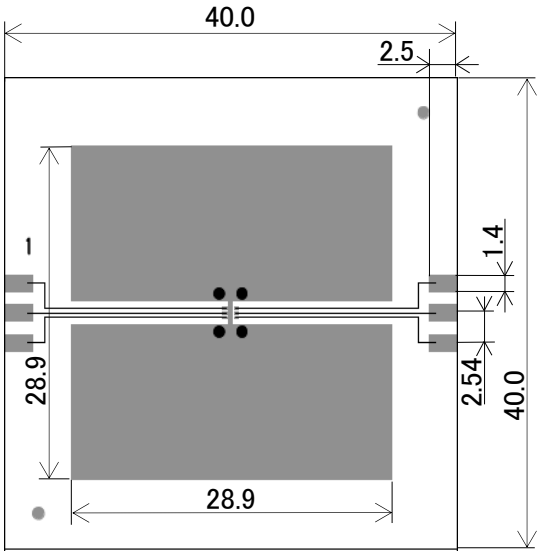


● DFN1515-6A Power Dissipation ※Tjmax=150℃

DFN1515-6APower dissipation data for the DFN1515-6A is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as the reference data taken in the following condition.

1. Measurement Condition

Condition: Mount on a board
Ambient: Natural convection
Soldering: Lead (Pb) free
Board Dimensions: 40 x 40 mm (1600mm2 in one side)
1st Meter layer: About 50%
2nd Meter layer: About 50%
3rd Meter layer: About 50%
4th Meter layer: About 50%
Each heat sink back metal is connected to the Inner layers respectively.
Material Glass Epoxy (FR-4)
Thickness 1.6mm
Through-hole 4 x 0.8 Diameter



Evaluation Board Layout(Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (Tjmax = 150℃)

Ambient Temperature (℃)	Power Dissipation Pd(mW)		θja(℃/W)
	Ta max=125℃	Ta max=150℃	
25	1000	1000	125.00
125	200	200	
150	0	0